

**Amendments to the Specification**

Please amend the title as follows

MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND MANUFACTURING  
METHOD OF THE SAME

Please amend the paragraph beginning at page 1, line 4 as follows:

This application is a divisional application of U.S. Patent Application Serial No.  
09/865,704, which is based on Japanese Patent Application Nos. No. 2000-159685 filed on May  
30, 2000, the contents of which are incorporated herein by reference.